



CERN

**TS-DEM**

**Development of Electronic Modules  
Group**

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**Erik van der Bij**  
**CERN**

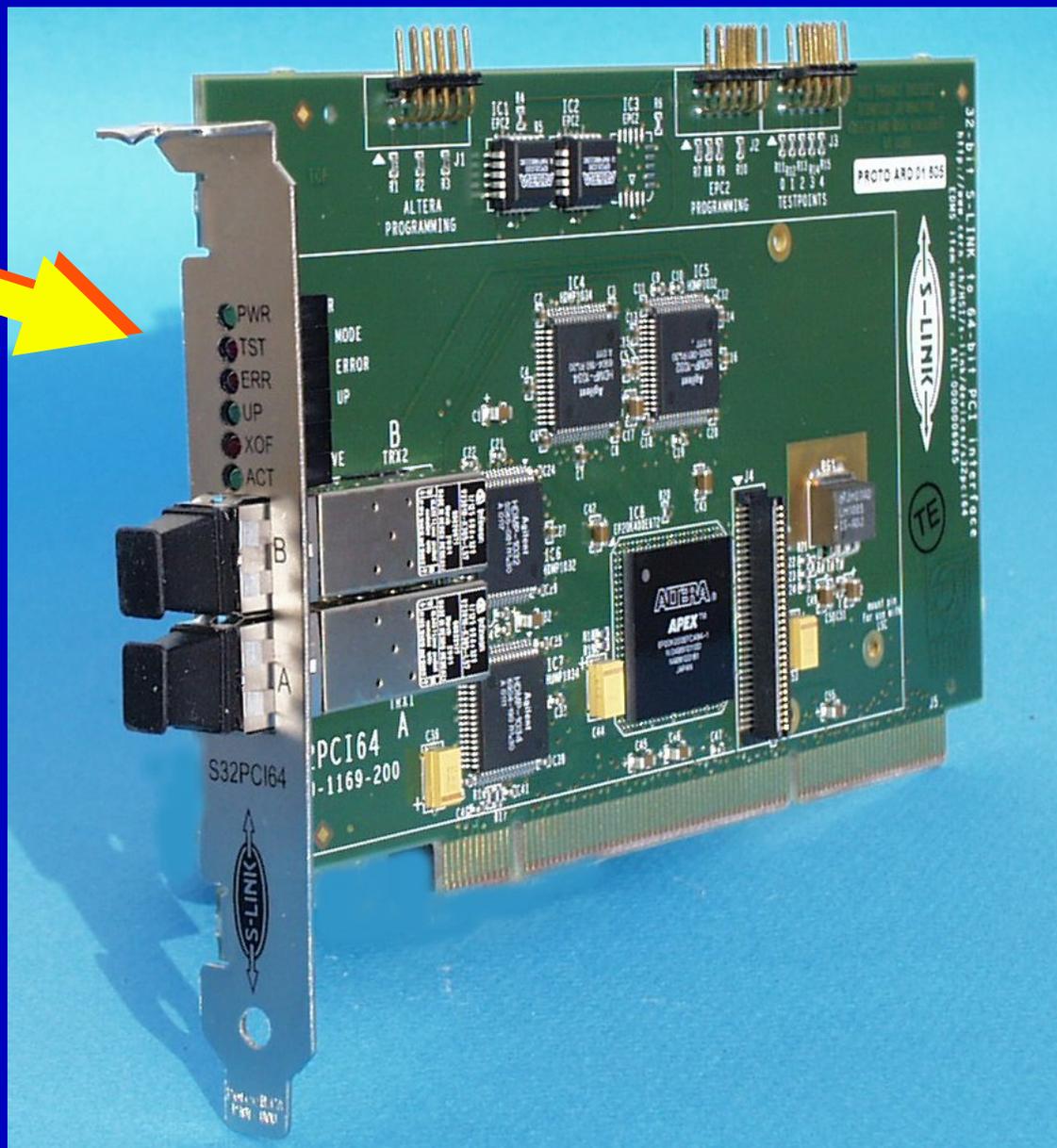
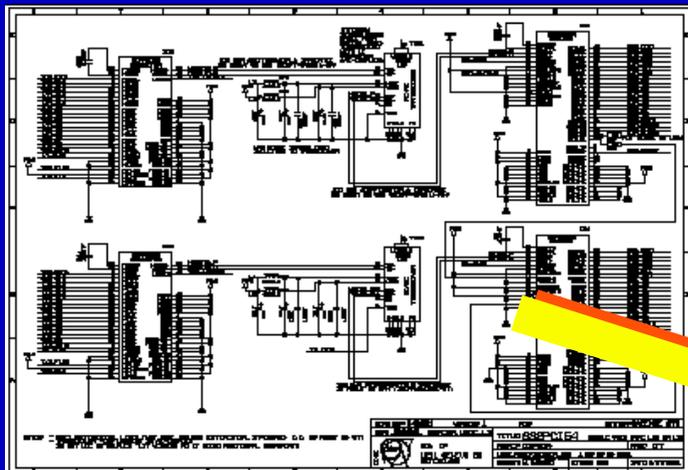
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# Agenda

**Services and organisation of TS-DEM**

**Organisation of files in EDMS (AB/PO)**

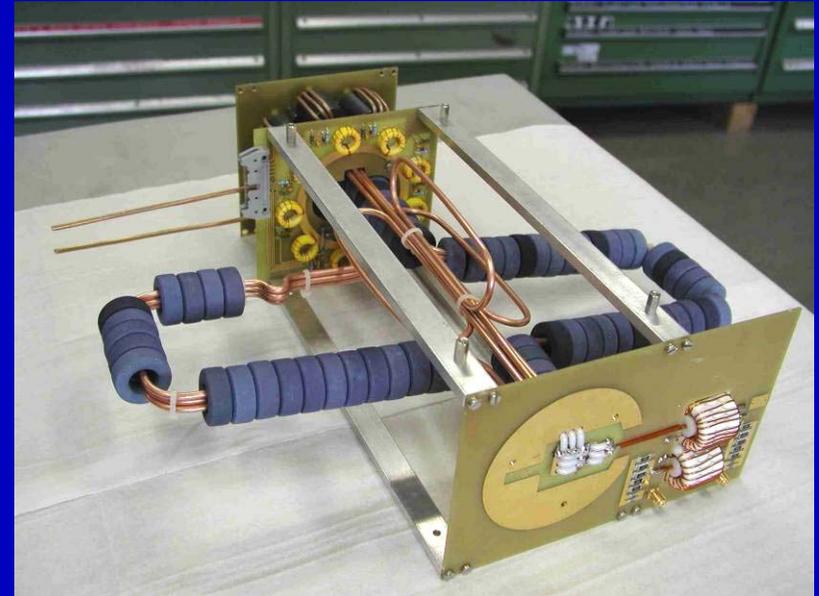
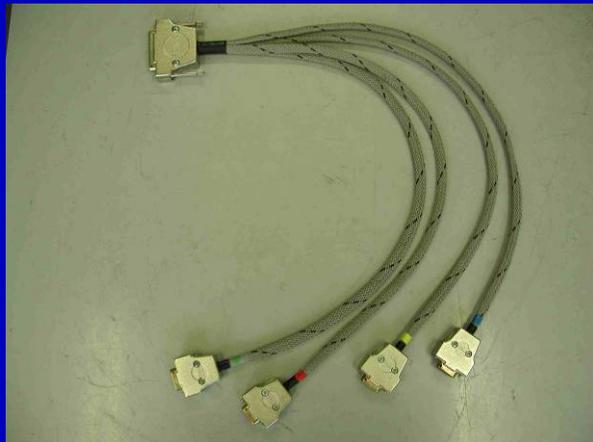
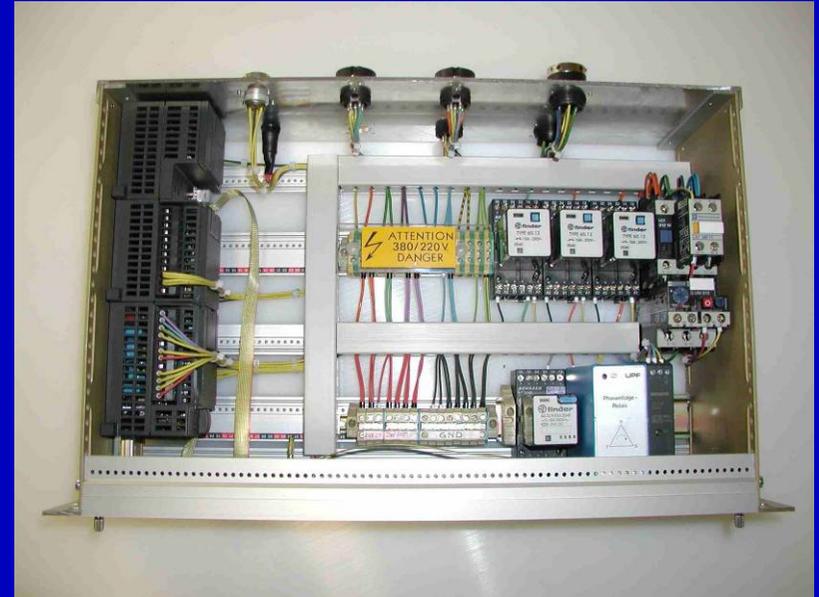
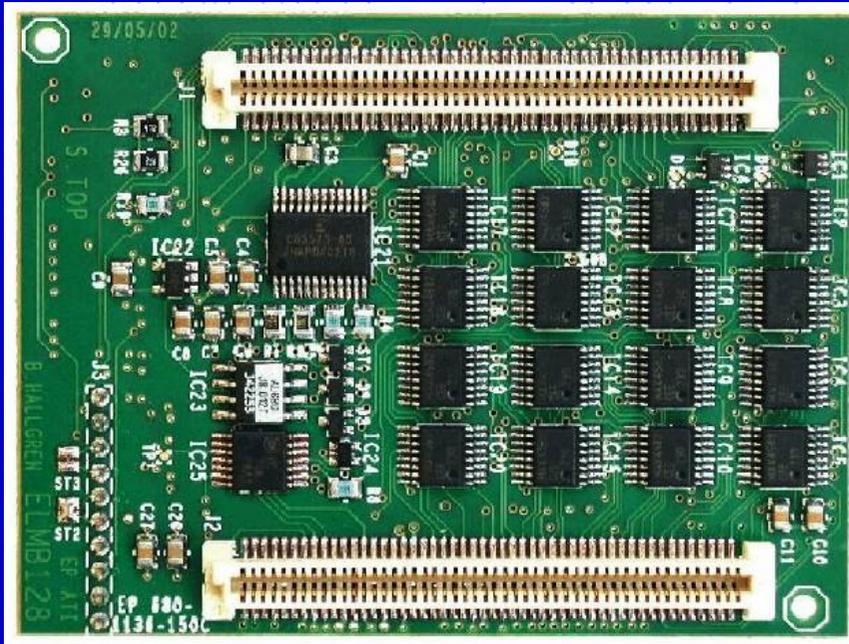
**Reliability engineering**



**MANDATE**  
**Turn schematics  
into boards  
(standard + special)**

- PCB design
- Manufacture of  
special circuits  
and PCBs
- Assembly

# Examples of "standard" work

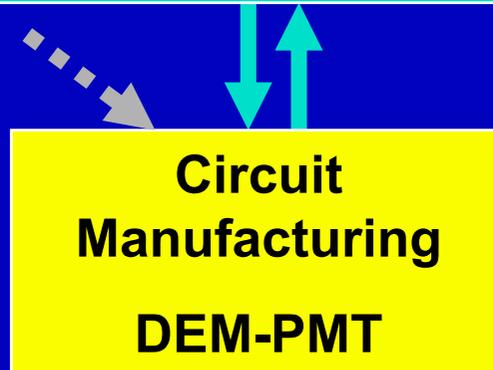
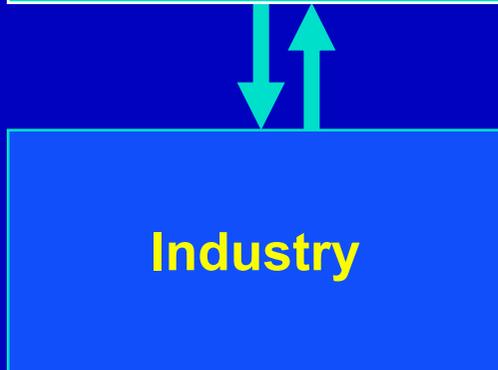




# TS-DEM

Request

Circuit or module



# BE – Design office

## Betty Magnin

**Layout of PCB, flexible circuit, hybrid or fine-pitch detectors**

**Design of associated small mechanics (front-panels, crates)**

**Creation of schematic and padstack symbols**

- Cadence and PCAD/Altium libraries

**Storage of manufacturing files**

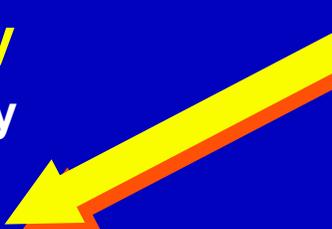
- PCB production, assembly, bill of material all in EDMS (EDA-xxxxx)

**Organisation of production and assembly**

- prototype quantities: in-house or local industry
- larger quantities: European industry

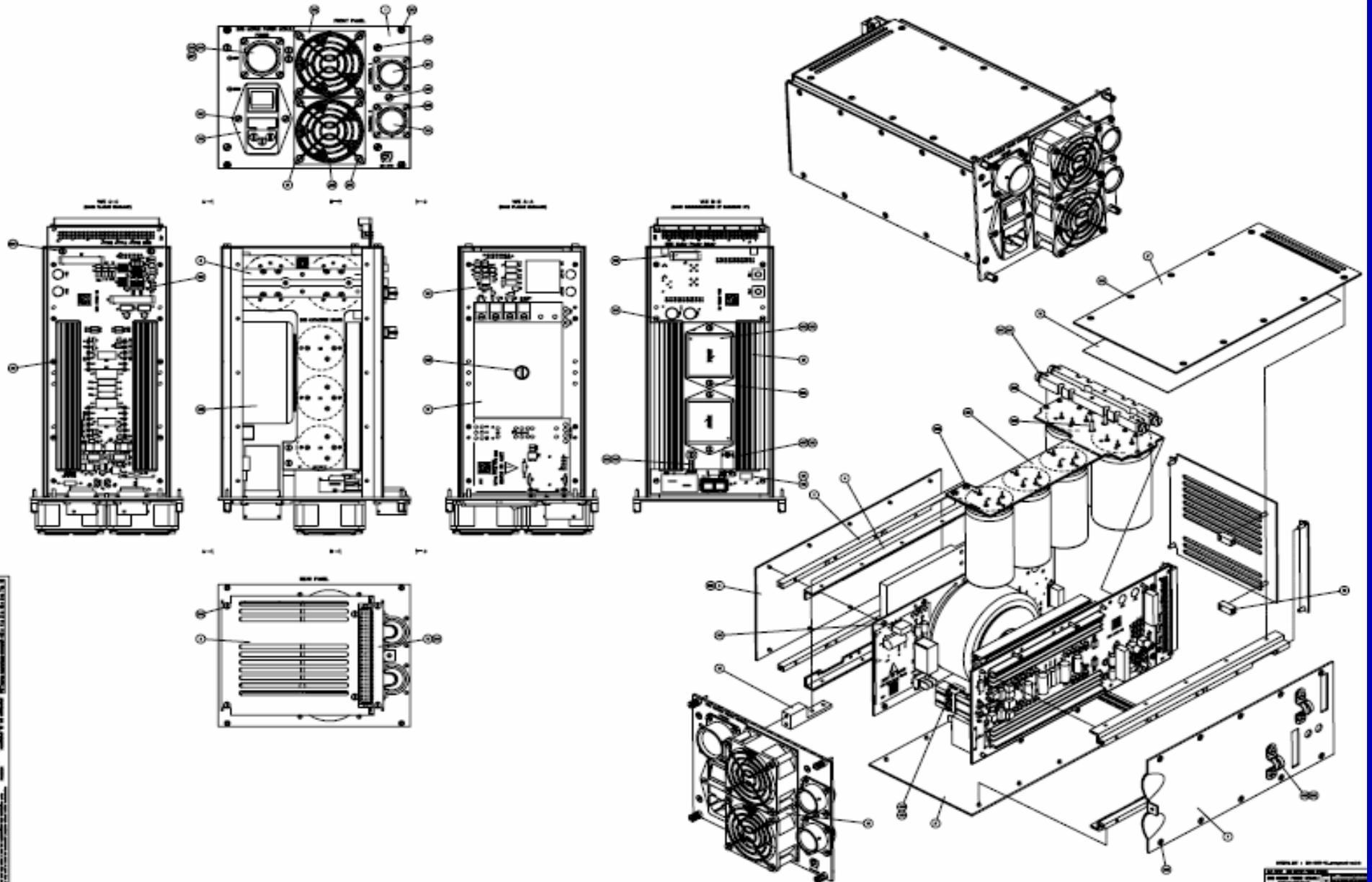
**Component purchasing service (new!)**

**Technical advice on manufacturing**



**Easy way  
to save  
time!**

# Example of mechanics



# PMT – Fabrication

## Rui de Oliveira

### Special circuits

- flex-rigid boards
- multi-layer boards with integrated metal or pyrolytic carbon
- high-definition circuits (traces and isolation 5 to 10  $\mu\text{m}$ )

### Thick-film hybrids

- serigraphy of conducting paste on ceramic substrates (aluminium, aluminium nitride, berillyumoxide)

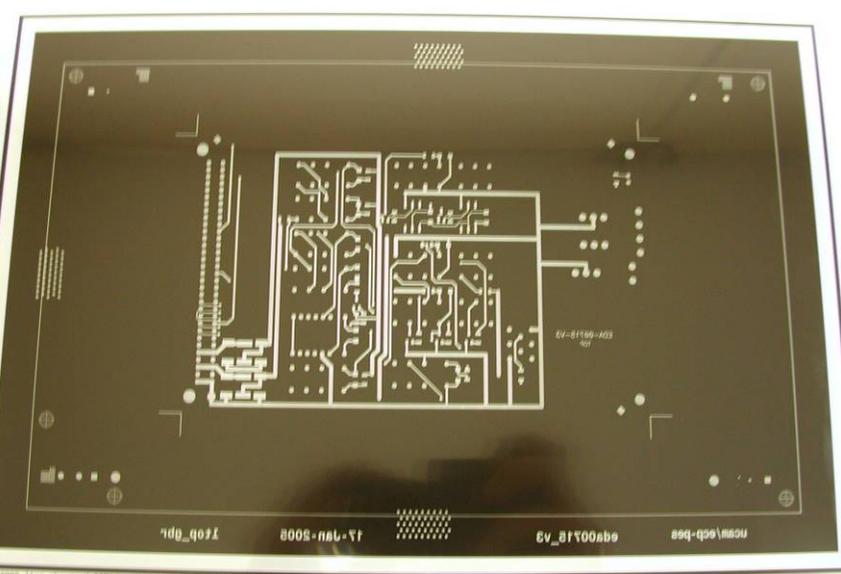
### Chemical treatment

- thin metal sheets (copper, inox, nickel, aluminium, titanium)

### Standard printed circuit boards (halogen free!)

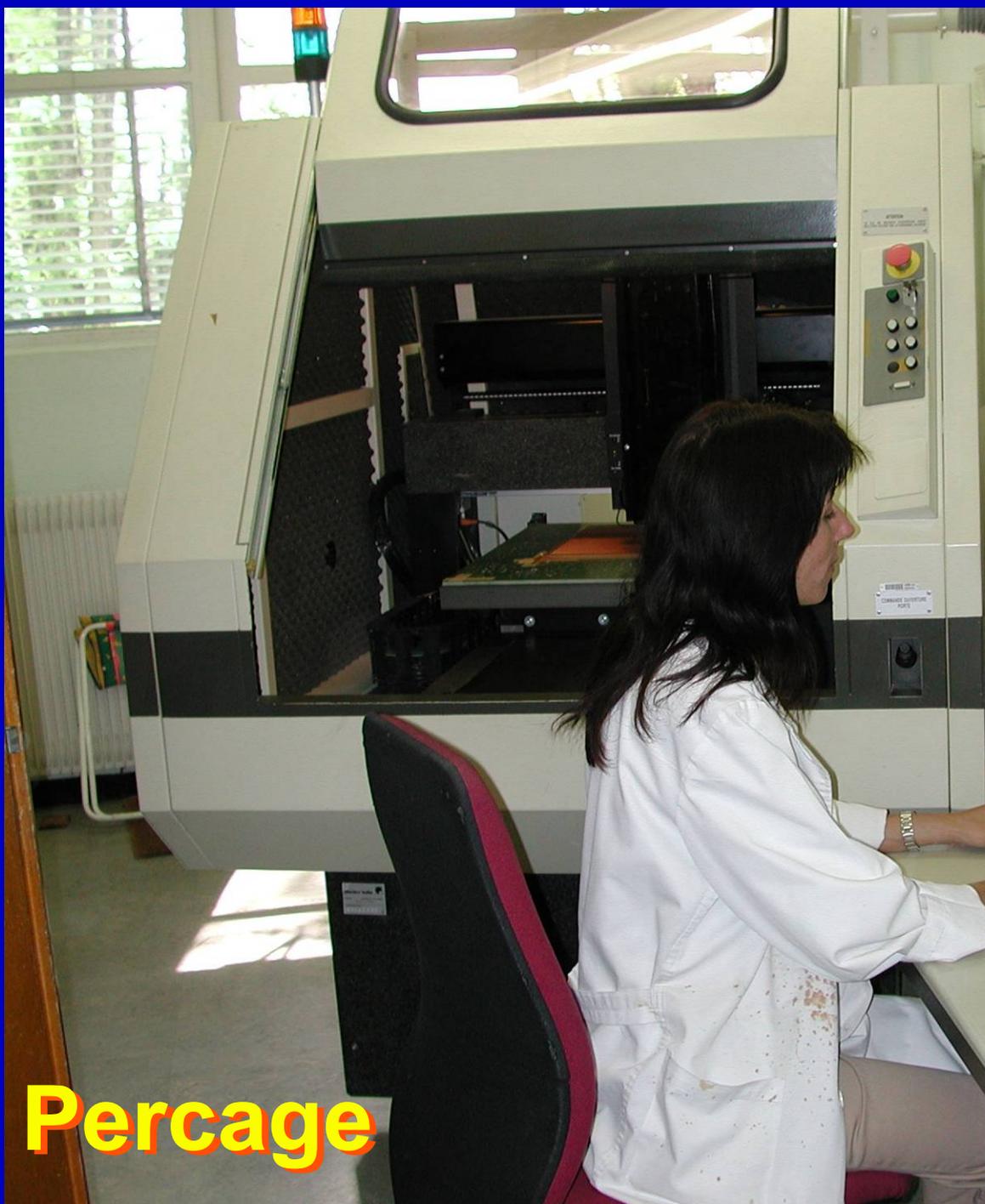
- single side to multi-layer boards (upto 14 layers, class 6)
- flexible circuits (kapton)

### Technical advice on material selection and processes



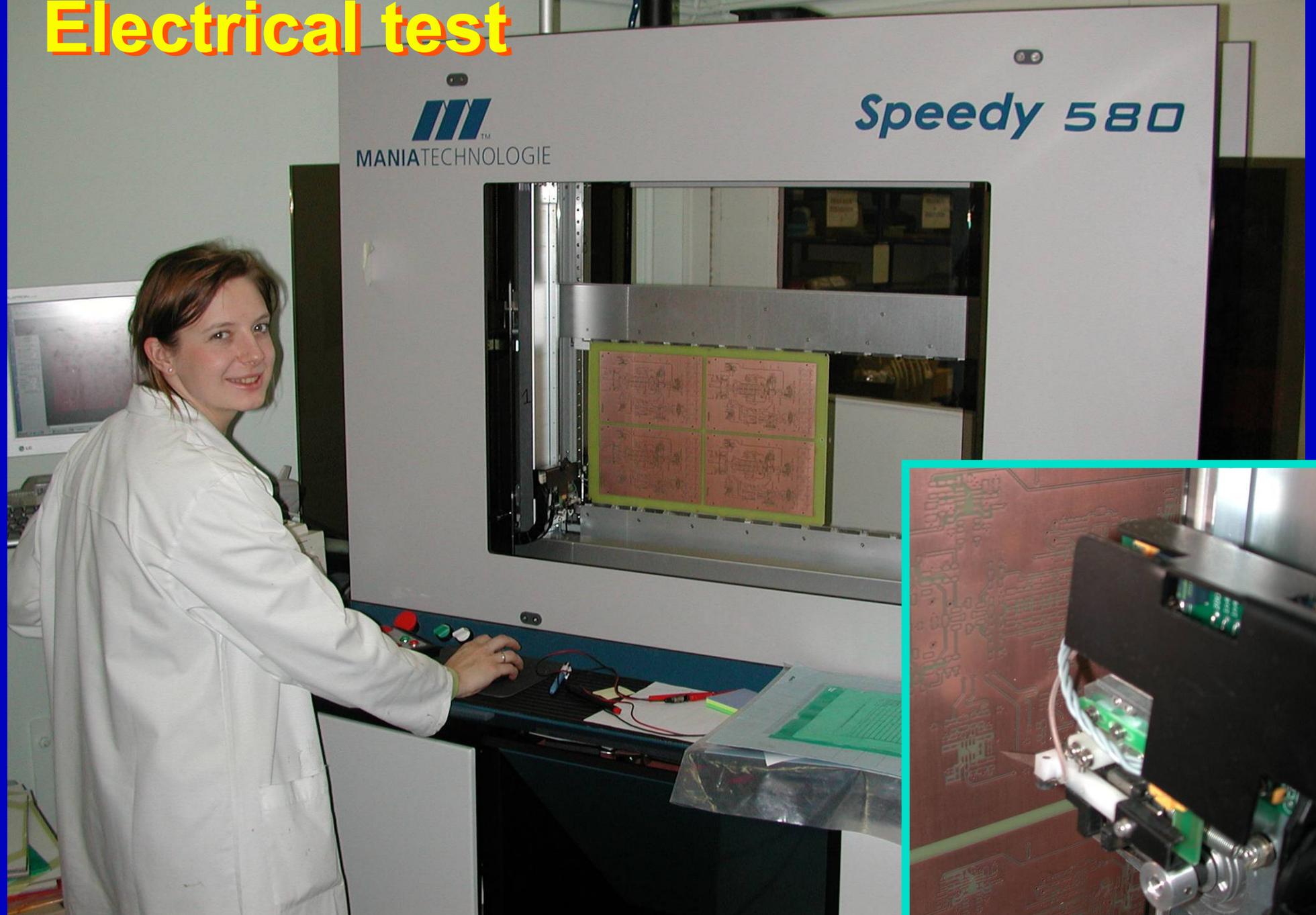
# Transfer Image





**Percage**

# Electrical test



# WS – Assembly workshop

## Betty Magnin



### Mounting of components

- through-hole
- BGA down to 0.8 mm pitch
- resistors and capacitors down to 0201 size

### Replacing of components, including BGA

### Production of cables (coax, flatcables, twisted pair)

### Wiring of crates

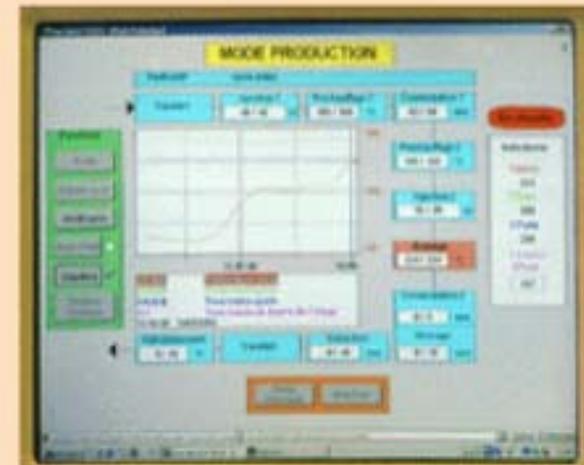
### 30-minute express service for small interventions

### Cleaning of boards

### Technical advice

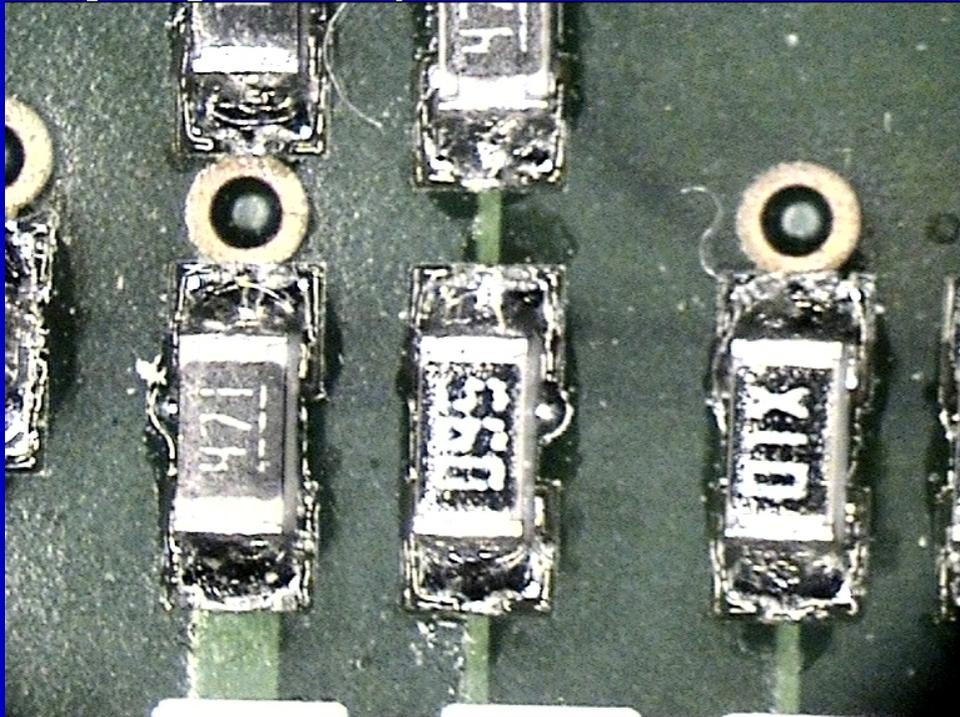
- component selection and manufacturing

# Condensation oven



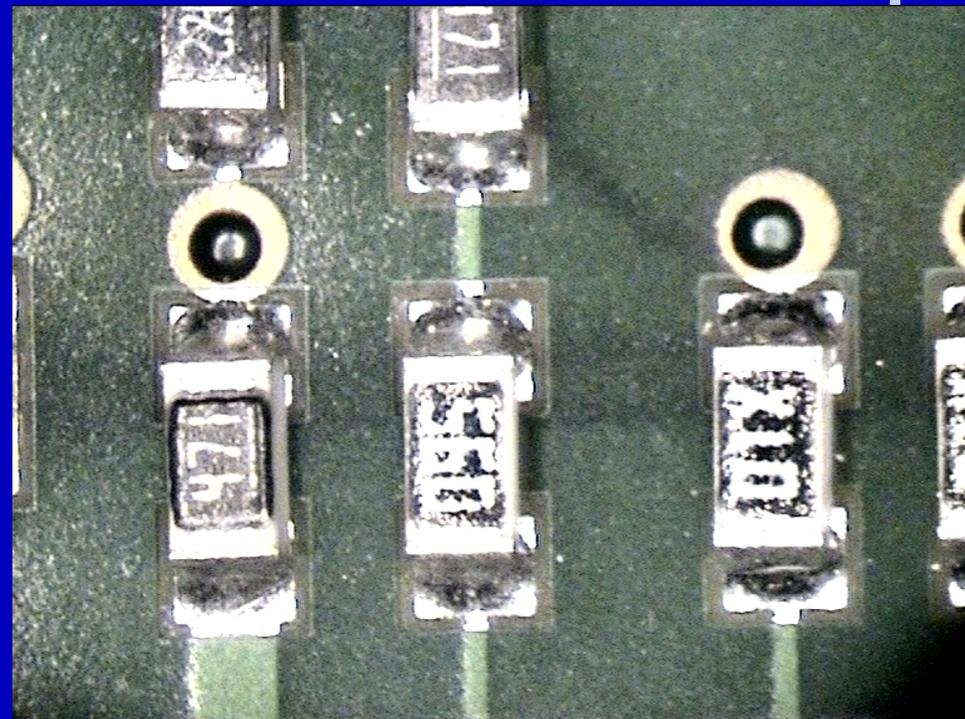
Brasage écran

# Cleaning of circuits



**Before cleaning**

**After cleaning**



# Turn-around time

Prototype electronics production  
multi-layer PCB, standard priority

Layout (and queue) 4 weeks	PCB fabrication 3 weeks	Assembly 2 weeks	Margin 1 week
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**This time can be reduced if necessary!**

**PCB fabrication can handle 2 urgencies per week**

– e.g. double sided PCB in 1 day, single sided 0.5 day

**Replacement of component: 30 minute service**

# PCB Delivery times

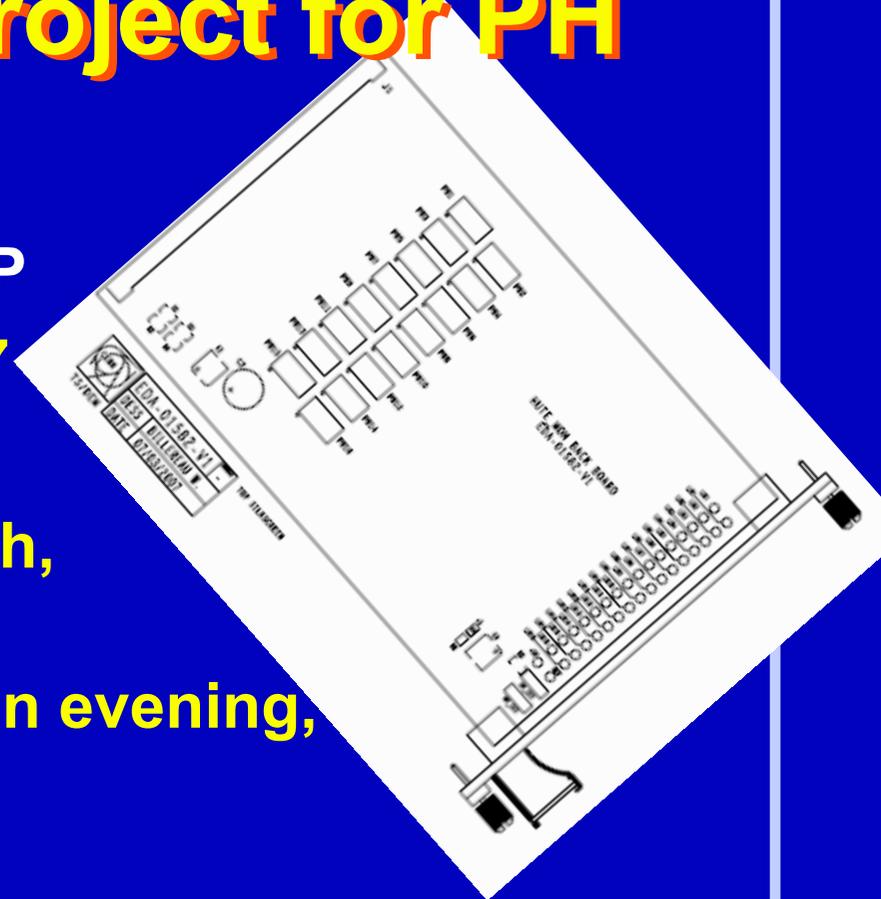
Type	Urgent [days]	Standard [days]
Single sided		1
Double sided with metallised vias	1	5
4 and 6 layer with metallised vias	3 or 6	10
> 8 layers with metallised vias	3 or 6	15

**Fast track PCB layout (since July 2007):**

**Small jobs (estimated  $\leq 2$  days) will be started immediately or on next day**

# Example: Urgent full project for PH

- Layout and PCBs needed ASAP
- Received request 7 March 2007
- Same day layout finished!
- 4 PCBs ready on Friday 9 March, rest on Monday after
- Assembled 1 PCB on Friday 9 in evening, second finished on the 12th.



# Example: Urgent project for AB/CO

- Layout ready: three different PCBs needed ASAP
- Needed really fast:
  - no solder masks or silkscreen finish needed
- Design files given Friday 30 March 7:00
- PCBs ready same day at 15:00!
- Could have assembled connectors if needed
- Two weeks later tests finished, production of series requested

# Conclusions

## DEM provides you a turn-key solution

- from your schematics to assembled boards
- all services close to the engineers
- production in small to medium quantities
- advice on manufacturing (material, components, processes)

## DEM has contracts with industry

- local industry for prototyping
- in other CERN member states for medium scale production

## The service can save you a lot of time and cost

CERN

<http://cern.ch/dem>

**DEM**  
**on**  
**the**  
**web!**



**DEM**

Development of  
Electronic Modules



Layout, production and assembly of printed circuit boards, flexible circuits, ceramic hybrids and fine pitch detectors are the fields for which the DEM Group in the TS Department provides CERN-wide support. The group concentrates on the development of prototype modules and can also manage small scale productions that are outsourced to industry.



Rui de Oliveira, section leader of DEM-PMT  
explaining PCB fabrication technology at CERN Training program

## General Information

- [News](#)
- [Overview and mandate](#)
- [Organisation chart \(pdf\)](#)
- [Contact us](#)

## Services

- [Layout](#)
- [Production](#)
- [Assembly and cabling](#)

## Products

- [Patents & technologies](#)
- [GEM detectors](#)
- [Examples](#)

## Other

- [Other CERN support for electronics](#)

# Storage of design files in EDMS

## Files stored in EDMS since 2002

<http://edms.cern.ch/nav/eda-xxxxx>

BE: Schematics, PCB design & production,  
BOM & assembly files, mechanics

User: specification, images, supplier info

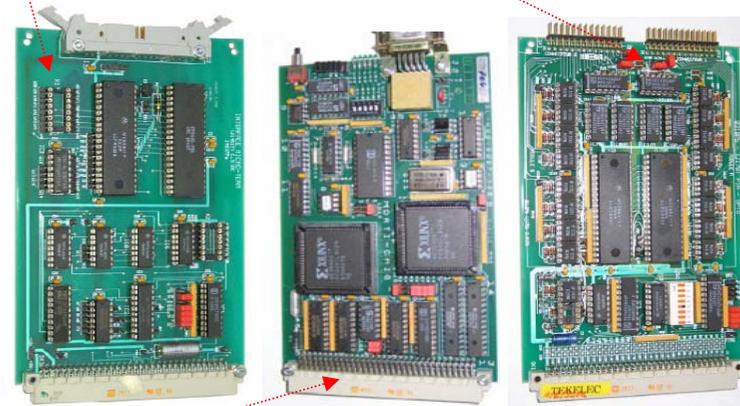
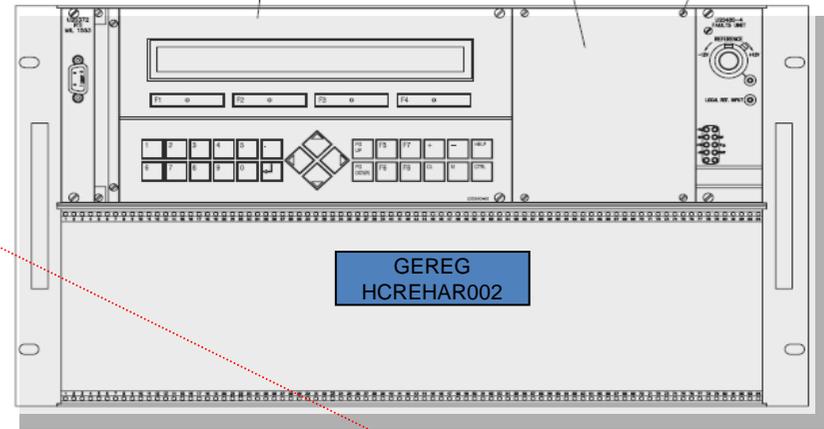
## Handling of 'executions' since 2006

project with AB/PO

# Enregistrement des cartes fabriquées par TS/DEM



- HCREHAR002 : GREG
- HCRBSCD00A : 14617P : Interface Micro-Term
- HCRNDAA000 : Clavier - Afficheur 50TE
- HCRBABH000 : Supervision CPU Mitsubishi
- HCRBSEI00A : 0310P : PIA-OPTO
- HCRBSEI00B : 0310P : PIA-OPTO
- HCRBSCO001 : DC-DC Relays
- HCRBSCP001 : Interface Burndy (8p) to Flat Cable
- HCRBSCQ001 : Interface Burndy (12p) to Flat Cable
- HCRBSCR001 : Interface Burndy (19p) to Flat Cable
- HCRBSCS001 : Interface Burndy (28p) to Flat Cable
- HCRB SCT002 : Backplane
- HCRBSCU00D : 24743P : Analog Measures (Protection)
- HCRBSCV00C : Faults Unit
- HCRBSCW003 : Supervision Interface
- HCRBSCX003 : Multianalogue
- HCRBSCY003 : Interface G64 to Multianalogue
- HCRBSCZ002 : Loop for PWM
- HCRBSDA002 : PWM
- HCRB SDB001 : DSP
- HCRB SDC003 : Loop Thyristor
- HCRB SDD003 : Gate Control
- HCRB SDS001 : G64 Bus / 6 Positions
- HCRB SDT001 : Electronics for DCCT
- HCRB SBW000 : MDRTI-CMIG 1553

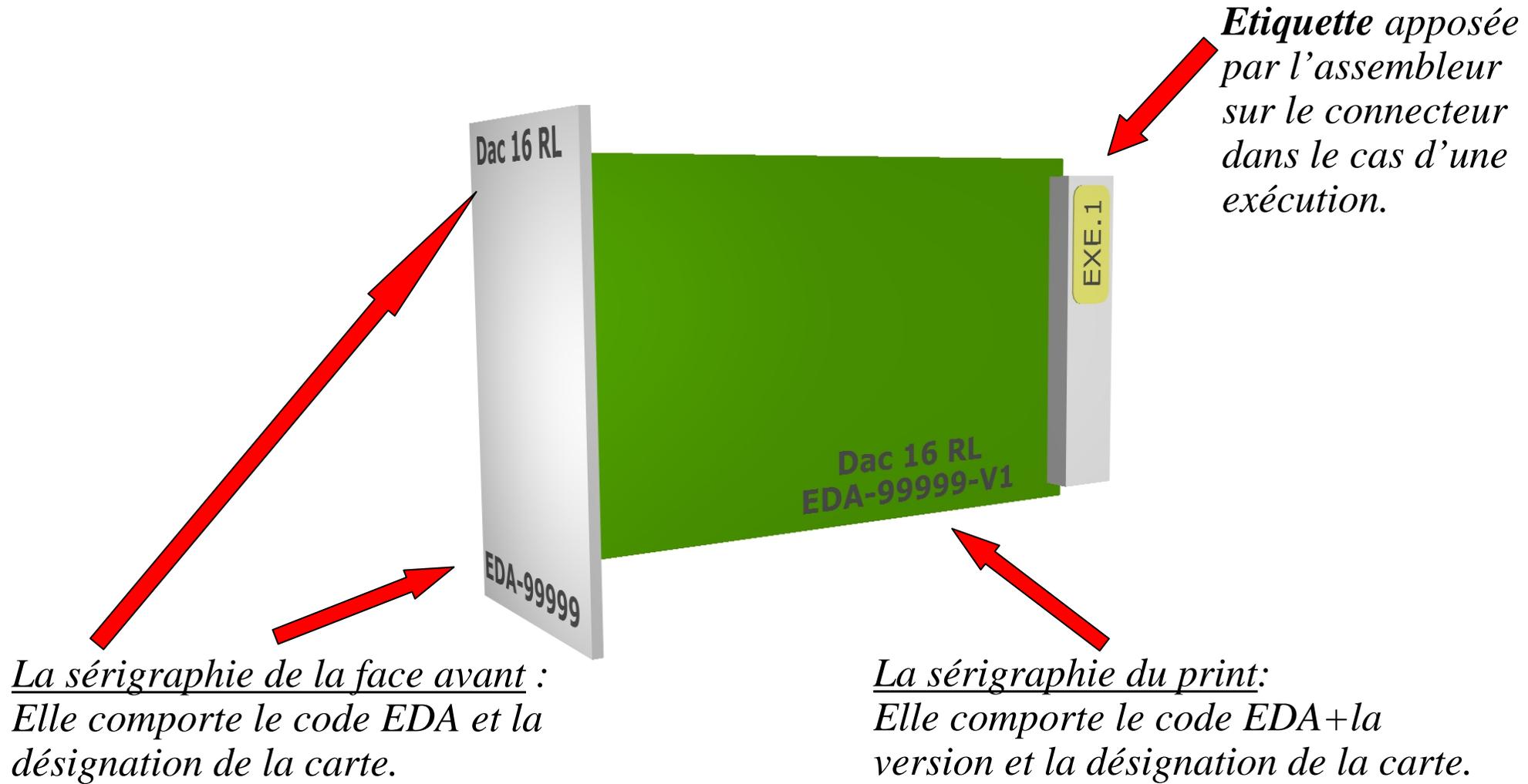
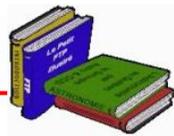


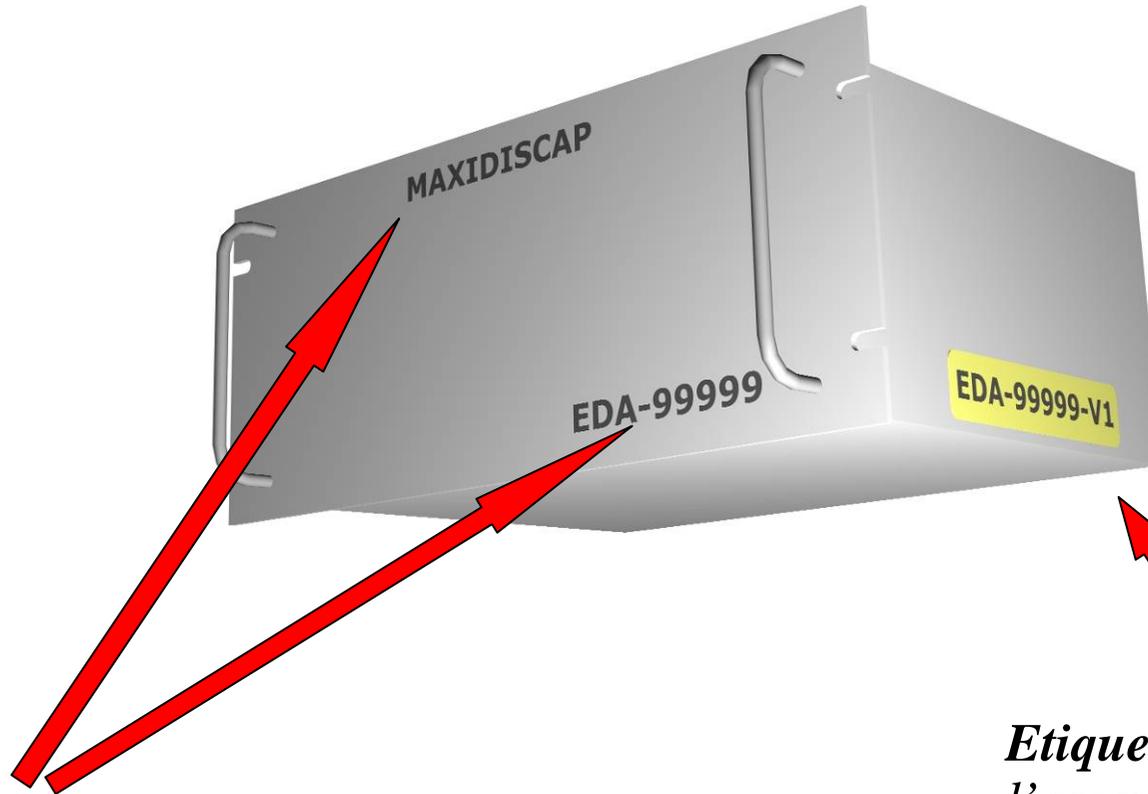
CERN CH-1211 Geneva 23 Switzerland	AB-PO Production
abpo Accelerator converter group Trieste	801714 v.1 Production Documentation management
Date: 08/11/2006	
<b>CONVENTION</b>	
<b>ORGANISATION ET GESTION DES DOSSIERS DE FABRICATION DES CHASSIS ET DES CARTES ELECTRONIQUES PRODUITS PAR TS/DEM</b>	
08/07	
<p>Cette convention, produite dans le cadre d'une collaboration entre TS-DEM et AB-PO définit l'organisation et la gestion des dossiers de fabrication des chassés et des cartes électroniques produits par le bureau d'Abpo TS-DEM de manière à ce que les documents de la convention soient des documents officiels auprès Documentation Trieste de Management.</p> <p>Elle a été élaborée en collaboration de cette convention à l'ensemble de tous les bureaux de fabrication.</p>	
Produit par :	Approuvé par :
GERMAIN BONNE Ludovic COLLETTI Anthony COLLETTI Massimo BALLETTI Paolo MAGNIN Betty PROCIER Christophe BURONT Marc	Validé par : MAGNIN Betty PROCIER Christophe
	Approuvé par : VAN DER ELK Erik TIEBER Rainer BOESBY Frederick

**Selon convention signée par AB-PO et TS-DEM**  
 (Document EDMS 801714 v1)  
**1 carte: HCRBSxxxxx = EDA-yyyyy-Vx-x**  
**Un dossier de fabrication unique**

Code de fabrication TS-DEM: EDA-xxxxx-Vx-x  
 Code d'exploitation AB-PO : HCRBSxxxxx







La sérigraphie de la face avant :  
*Elle comporte le code EDA et la désignation du chassis.*

*Etiquette apposée par l'assembleur pour spécifier la version.*

# Dossiers de fabrication TS/DEM - Example en EDMS



The screenshot shows the EDMS ADC web interface. The browser window title is "EDA-99999". The page header includes navigation links: Home, Navigator, Search, Help, EDMS Site, Caddie, Logout. The user is identified as MBOMONT. The main content area displays document details for "DAC 16 RL" with EDMS Id: EDA-99999-V2-0 v.0. The document is in "In Work" status. The interface lists four documents in this node:

EDMS Id	Description	Status
608417 v.1	ADC schematics	In Work
608425 v.1	ADC PCB-Layout	In Work
608434 v.1	ADC Assembly Data	In Work
798024 v.1	ADC Board Manufacturing Data	In Work

Each document entry includes a "Doc. page" link, file names (e.g., EDA-99999-V2-0\_sch.pdf), sizes (6 Kb), and version information (0 sub-doc, 1 version). The user Patrice BAILLY is associated with the first three documents, and Marc BOMONT with the last one. The footer shows "EDMS 3.9.4 @CERN - 2006.11.17 - 08:00:48" and a "Local intranet" icon.

Example:  
<http://edms.cern.ch/nav/eda-01586>